

Steven
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Attorney Docket No. 17732-3856000

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.:
Date of Filing: 3/30/01
Inventors: Chong; Lee; Allen; Martin
Assignee: Fairchild Semiconductor Corporation
Title: Packaging System for Die-Up Connection of a Die-Down Oriented Integrated Circuit

1c930 U.S. PTO
09/823600



INFORMATION DISCLOSURE STATEMENT
WITHIN 3 MONTHS OF FILING OR PRIOR TO FIRST OFFICE ACTION

Commissioner for Patents,
Washington, DC 20231

Dear Sir:

A list of documents on form PTO-1449 (six citations) together with copies of each identified document and a translation or a concise explanation of each non-English language document is submitted in the above identified application in compliance with 37 CFR 1.97 & 1.98. This paper is submitted in accordance with 37 CFR 1.97(b) (within three (3) months of the application filing date or prior to a first Office Action on the merits).

Please charge any fees, or apply any credits, in connection with this matter to Deposit Account No. 500282.

Respectfully submitted,

Chris A. Caseiro

Mar. 30, 2001

Date

Customer Number:

Chris A. Caseiro, Reg. No. 34,304
Attorney for Applicants



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PATENT TRADEMARK OFFICE

CERTIFICATE OF MAILING

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I hereby certify under 37 CFR 1.10 that this correspondence is being deposited with the United States Postal Service as "Express Mail Post Office to Addressee" with sufficient postage on the date indicated above and is addressed to the Assistant Commissioner for Patents, Washington, DC, 20231.

Constance S. Rogers

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